



SOT1830-1

plastic thermal enhanced very thin quad flat package; no leads; 28 terminals; body 3.5 x 5.5 x 0.85 mm

26 April 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN28
Package type industry code	HVQFN28
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MO-220
Mounting method type	S (surface mount)
Issue date	26-4-2016

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	5.4	-	5.5	5.6	mm
E	package width	3.4	-	3.5	3.6	mm
A	seated height	0.8	-	0.85	1	mm
e	nominal pitch	-	-	0.5	-	mm
n ₂	actual quantity of termination	-	-	28	-	

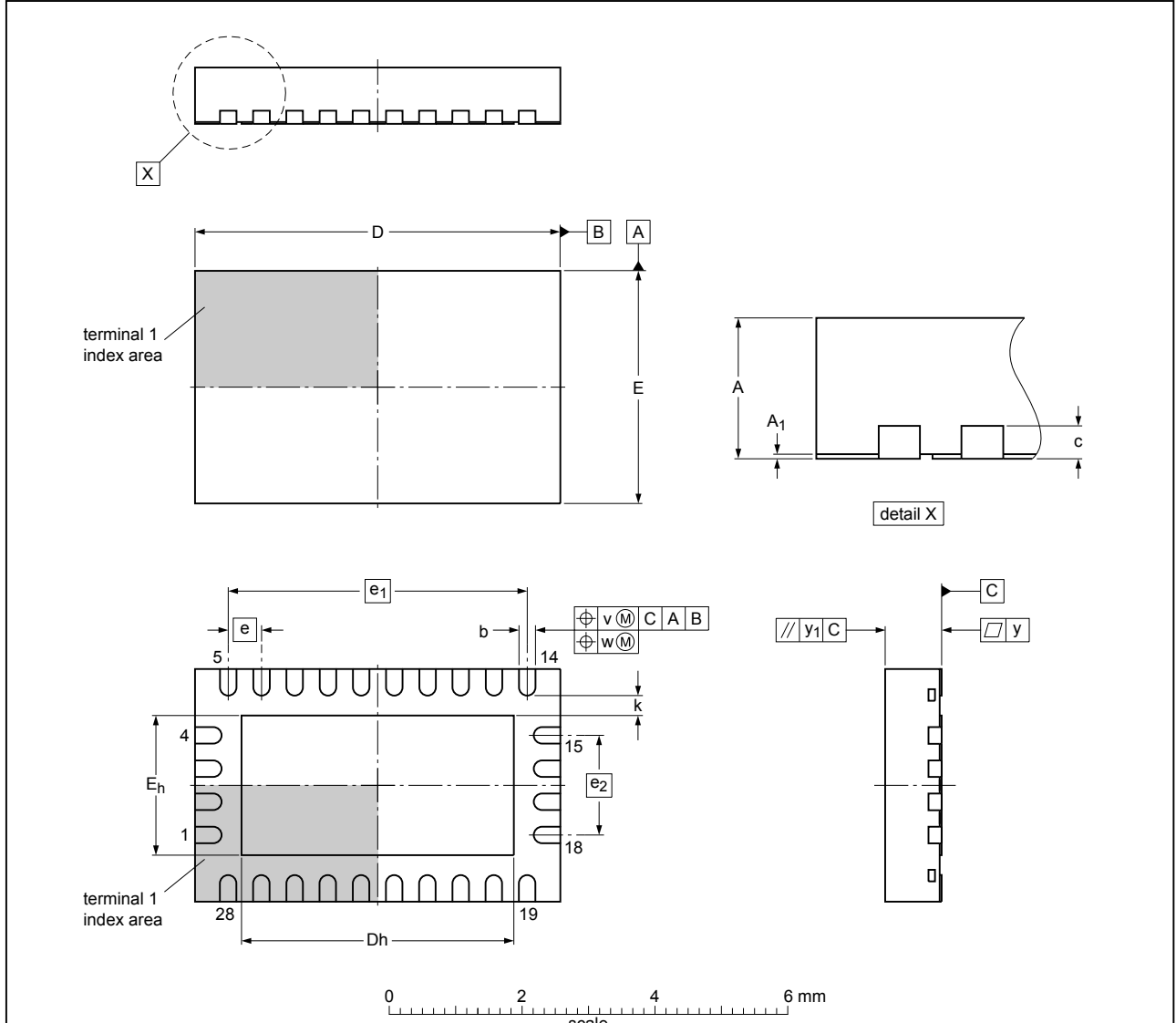


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2. Package outline

HVQFN28: plastic thermal enhanced very thin quad flat package; no leads; 28 terminals; body 3.5 x 5.5 x 0.85 mm

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Dimensions (mm are the original dimensions)

Unit	A ⁽¹⁾	A ₁	b	c	D ⁽¹⁾	D _h	E ⁽¹⁾	E _h	e	e ₁	e ₂	k	L	v	w	y	y ₁
max	1.00	0.05	0.30		5.60	4.15	3.60	2.15				0.35	0.45				
nom	0.85	0.03	0.25	0.2	5.50	4.10	3.50	2.10	0.5	4.5	1.5	0.30	0.40	0.1	0.05	0.05	0.1
min	0.80	0.00	0.20		5.40	4.05	3.40	2.05				0.25	0.35				

Note

1. Plastic or metal protrusions of 0.075 mm maximum per side are not included.

sol1830-1_po

Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT1830-1	---	MO-220	---		-16-01-20- 16-01-20

Fig. 1. Package outline HVQFN28 (SOT1830-1)

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3. Legal information

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